

# Silicon Carbide (SiC) **MOSFET** - 33 mohm, 650 V, M2, TO-247-4L

## NVH4L045N065SC1

#### **Features**

- Typ.  $R_{DS(on)} = 33 \text{ m}\Omega$  @  $V_{GS} = 18 \text{ V}$ Typ.  $R_{DS(on)} = 45 \text{ m}\Omega$  @  $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge (Q<sub>G(tot)</sub> = 105 nC)
- High Speed Switching with Low Capacitance (Coss = 162 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

## **Typical Applications**

- Automotive On Board Charger
- Automotive DC-DC Converter for EV/HEV

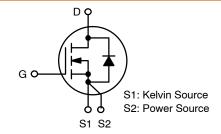
#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	650	V
Gate-to-Source Voltage	!		$V_{GS}$	-8/+22	V
Recommended Operation of Gate-to-Source Volta		T <sub>C</sub> < 175°C	$V_{GSop}$	-5/+18	>
Continuous Drain Current (Note 2)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	55	Α
Power Dissipation (Note 2)			P <sub>D</sub>	187	W
Continuous Drain Current (Notes 1, 2)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	39	Α
Power Dissipation (Notes 1, 2)			P <sub>D</sub>	94	W
Pulsed Drain Current (Note 3)	T <sub>C</sub> = 25°C		I <sub>DM</sub>	197	Α
Single Pulse Surge Drain Current Capability	$T_A$ = 25°C, $t_p$ = 10 $\mu$ s, $R_G$ = 4.7 $\Omega$		I <sub>DSC</sub>	315	Α
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Source Current (Body Diode)			I <sub>S</sub>	45	Α
Single Pulse Drain-to-S Energy (I <sub>L(pk)</sub> = 12 A, L =	in-to-Source Avalanche  2 A, L = 1 mH) (Note 4)		E <sub>AS</sub>	72	mJ
Maximum Lead Tempera (1/8" from case for 5 s)	ture for S	oldering	T <sub>L</sub>	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. JA is constant value to follow guide table of LV/HV discrete final datasheet generation.
- 2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. Repetitive rating, limited by max junction temperature.
- 4. EAS of 72 mJ is based on starting  $T_J = 25^{\circ}C$ ; L = 1 mH,  $I_{AS} = 12 A$ ,  $V_{DD} = 50 \text{ V}, V_{GS} = 18 \text{ V}.$

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	50 mΩ @ 18 V	55 A

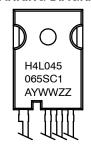


#### **N-CHANNEL MOSFET**



CASE 340CJ

#### **MARKING DIAGRAM**



H4L045065SC1 = Specific Device Code

= Assembly Location

= Year

WW = Work Week

= Lot Traceability

## **ORDERING INFORMATION**

Device	Package	Shipping
NVH4L045N065SC1	TO247-4L	30 Units / Tube

April, 2022 - Rev. 1

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 2)	$R_{ heta JC}$	0.8	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)	$R_{ heta JA}$	40	

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•			•	•		
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ mA}$		650	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 20 mA, referenced	d to 25°C	-	0.15	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C	-	-	10	μΑ
		V <sub>DS</sub> = 650 V	T <sub>J</sub> = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = +18/-5 \text{ V}, V_{DS}$	= 0 V	-	-	250	nA
ON CHARACTERISTICS (Note 3)	1	•				ı	I
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 8 \text{ mA}$		1.8	2.8	4.3	V
Recommended Gate Voltage	$V_{GOP}$			-5	-	+18	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 25 A,	T <sub>J</sub> = 25°C	-	45	-	mΩ
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 25 A,	T <sub>J</sub> = 25°C	-	33	50	
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 25 A,	T <sub>J</sub> = 175°C	-	41	_	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A		-	16	-	S
CHARGES, CAPACITANCES & GATE RES	ISTANCE	<b>.</b>					
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 325 V		-	1870	_	pF
Output Capacitance	C <sub>OSS</sub>			_	162	_	
Reverse Transfer Capacitance	C <sub>RSS</sub>	=		_	14	_	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$ $I_D = 25 \text{ A}$		-	105	_	nC
Gate-to-Source Charge	Q <sub>GS</sub>			_	27	_	
Gate-to-Drain Charge	$Q_{GD}$	=		_	30	_	
Gate-Resistance	R <sub>G</sub>	f = 1 MHz		_	3.1	_	Ω
SWITCHING CHARACTERISTICS, VGS = 1	10 V	<b>.</b>					
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -5/18 \text{ V},$		_	13	_	ns
Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 25 A,		_	14	_	
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$R_G = 2.2 \Omega$ inductive load		_	26	_	1
Fall Time	t <sub>f</sub>	illuuciive loau		_	7	_	
Turn-On Switching Loss	E <sub>ON</sub>			_	47	_	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>	- -		_	33	_	
Total Switching Loss	E <sub>tot</sub>			-	80	_	
DRAIN-SOURCE DIODE CHARACTERIST		1		1	1	1	
Continuous Drain-Source Diode Forward Current	I <sub>SD</sub>	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}\text{C}$		-	-	45	Α
Pulsed Drain-Source Diode Forward Current (Note 3)	I <sub>SDM</sub>			-	-	197	
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 25 A	, T <sub>J</sub> = 25°C	-	4.4	_	V

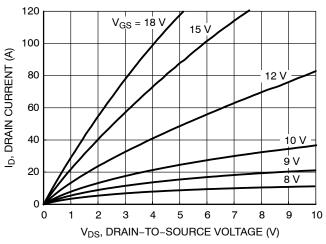
## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTERI	STICS		-			
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/18 \text{ V}, I_{SD} = 25 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}$	-	20	-	ns
Reverse Recovery Charge	Q <sub>RR</sub>	di <sub>S</sub> /dt = 1000 A/μs	-	108	-	nC
Reverse Recovery Energy	E <sub>REC</sub>		-	4.5	-	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	11	-	Α
Charge Time	Ta		-	11	-	ns
Discharge Time	Tb		_	8.5	_	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

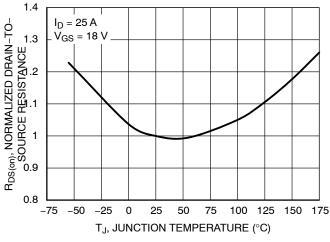
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Figure 1. On-Region Characteristics

Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage



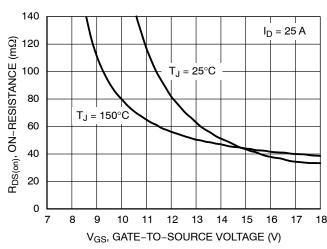
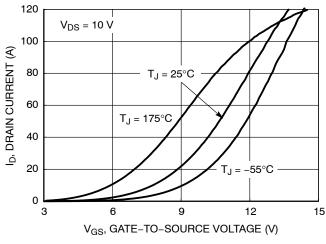


Figure 3. On–Resistance Variation with Temperature

Figure 4. On–Resistance vs. Gate–to–Source Voltage



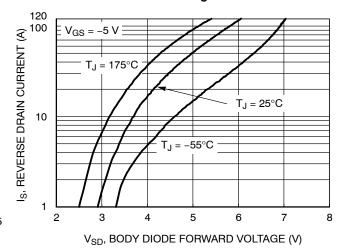


Figure 5. Transfer Characteristics

Figure 6. Diode Forward Voltage vs. Current

#### TYPICAL CHARACTERISTICS (continued)

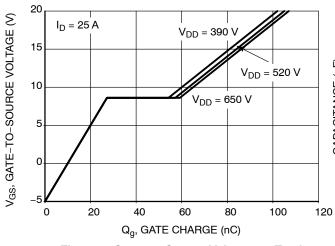


Figure 7. Gate-to-Source Voltage vs. Total Charge

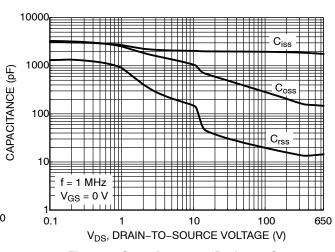


Figure 8. Capacitance vs. Drain-to-Source Voltage

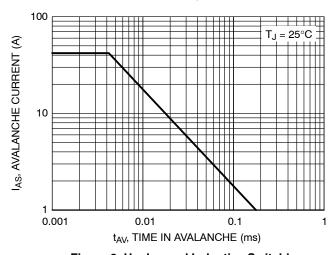


Figure 9. Unclamped Inductive Switching Capability

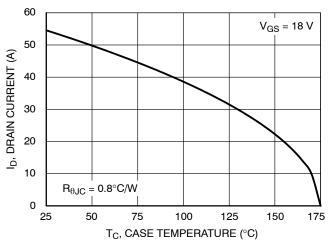


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

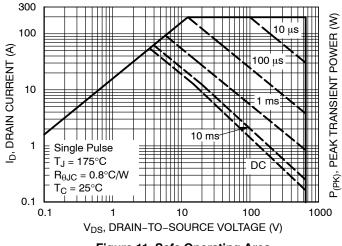


Figure 11. Safe Operating Area

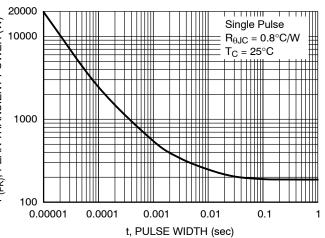


Figure 12. Single Pulse Maximum Power Dissipation

## TYPICAL CHARACTERISTICS (continued)

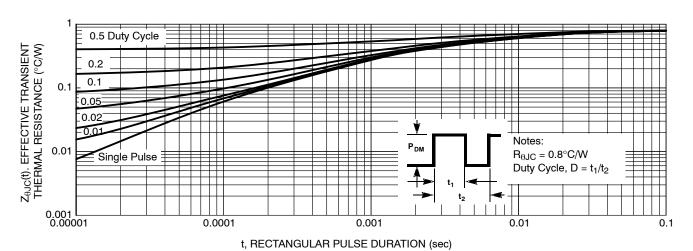


Figure 13. Junction-to-Case Thermal Response

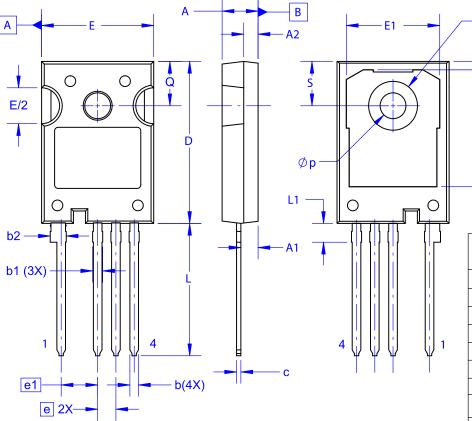
#### TO-247-4LD CASE 340CJ **ISSUE A**

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DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
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A2	1.80	2.00	2.20		
b	1.07	1.20	1.33		
b1	1.20	1.40	1.60		
b2	2.02	2.22	2.42		
С	0.50	0.60	0.70		
D	22.34	22.54	22.74		
D1	16.00	16.25	16.50		
D2	0.97	1.17	1.37		
е	2	2.54 BSC			
e1		5.08 BSC			
E	15.40	15.60	15.80		
E1	12.80	13.00	13.20		
E/2	4.80	5.00	5.20		
L	18.22	18.42	18.62		
L1	2.42	2.62	2.82		
р	3.40	3.60	3.80		
p1	6.60	6.80	7.00		
Q	5.97	6.17	6.37		
S	5.97	6.17	6.37		

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